TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

ULN2803AP,ULN2803AFW,ULN2804AP,ULN2804AFW (Manufactured by Toshiba Malaysia)

8CH DARLINGTON SINK DRIVER

The ULN2803AP / AFW Series are high-voltage, high-current darlington drivers comprised of eight NPN darlington pairs. All units feature integral clamp diodes for switching inductive loads.

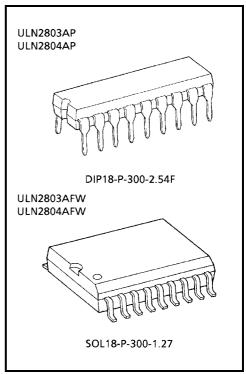
Applications include relay, hammer, lamp and display (LED) drivers.

FEATURES

- Output current (single output) 500 mA (Max.)
- High sustaining voltage output 50 V (Min.)
- Output clamp diodes

ULN2804AP / AFW

- Inputs compatible with various types of logic.
- Package Type-AP : DIP-18pinPackage Type-AFW : SOL-18pin



Weight

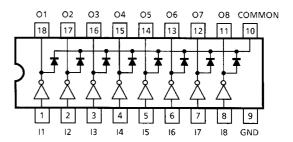
DIP18-P-300-2.54F: 1.478 g (Typ.) SOL18-P-300-1.27: 0.48 g (Typ.)

TYPE INPUT BASE RESISTOR DESIGNATION ULN2803AP / AFW 2.7 kΩ TTL, 5 V CMOS

 $10.5 \text{ k}\Omega$

6~15 V PMOS, CMOS

PIN CONNECTION (TOP VIEW)



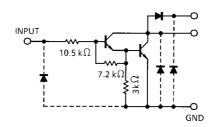


SCHEMATICS (EACH DRIVER)

ULN2803AP / AFW

INPUT O COMMON O OUTPUT $2.7 \text{ k}\Omega$ G

ULN2804AP / AFW



Note: The input and output parasitic diodes cannot be used as clamp diodes.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Output Sustaining Voltage		V _{CE (SUS)}	-0.5~50	V	
Output Current		lout	500	mA / ch	
Input Voltage		V _{IN}	-0.5~30	V	
Clamp Diode Reverse Voltage		V _R	50	V	
Clamp Diode Forward Current		lF	500	mA	
Power Dissipation	AP	D-	1.47	W	
	AFW	P _D	0.92 / 1.31 (Note)		
Operating Temperature		T _{opr}	-40~85	°C	
Storage Temperature		T _{stg}	-55~150	°C	

Note: On Glass Epoxy PCB (75 × 114 × 1.6 mm Cu 20%)



RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT	
Output Sustaining Volt	age	V _{CE} (SUS)		0 — 50		50	V	
Output Current	АР	- Іоит	T _{pw} = 25 ms, Duty = 10%, 8 Circuits	0	_	347		
			T _{pw} = 25 ms, Duty = 50%, 8 Circuits	0	_	123	mA / ch	
	AFW		T _{pw} = 25 ms, Duty = 10%, 8 Circuits	0	_	268		
			T _{pw} = 25 ms, Duty = 50%, 8 Circuits	0	_	90		
Input Voltage	ut Voltage			0	_	30	V	
Input Voltage	ULN2803AP / AFW	Mariana		3.5	_	30	V	
(Output On)	ULN2804AP / AFW	V _{IN} (ON)		8	_	30		
Clamp Diode Reverse Voltage		V _R		-	_	50	V	
Clamp Diode Forward Current		I _F		-	_	400	mA	
Power Dissipation	AP	D-	Ta = 85°C	_	_	0.76	W	
	AFW	P _D	Ta = 85°C (Note)	-	_	0.48	VV	

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Note: On Glass Epoxy PCB (75 × 114 × 1.6 mm Cu 20%)



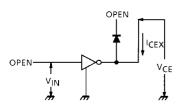
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHAF	RACTERISTIC	SYMBOL	TEST CIR- CUIT	TEST CONDITION		MIN	TYP.	MAX	UNIT	
Output Leakage Current ULN2804AP / AFW		I _{CEX}	1	V _{CE} = 50 V	Ta = 25°C	_	_	50	μА	
				V _{CE} = 50 V	Ta = 85°C	1	_	100		
				V _{CE} = 50 V	V _{IN} = 1 V		_	500		
Collector-Emitter Saturation Voltage		VCE (sat)	2	I _{OUT} = 350 mA,	I_{IN} = 500 μ A	1	1.3	1.6		
				I _{OUT} = 200 mA, I _{IN} = 350 μA		1	1.1	1.3	V	
				I _{OUT} = 100 mA, I _{IN} = 250 μA		1	0.9	1.1	ı	
Input Current	ULN2803AP / AFW			V _{IN} = 3.85 V		ı	0.93	1.35	mA	
	ULN2804AP / AFW	I _{IN (ON)}	2	V _{IN} = 5 V		-	0.35	0.5		
	ULN2804AP / AFW			V _{IN} = 12 V		_	1.0	1.45		
		I _{IN (OFF)}	4	I _{OUT} = 500 μA, Ta = 85°C		50	65	_	μΑ	
	ULN2803AP / AFW	Vin (on)	5	V _{CE} = 2 V, I _{OUT} = 200 mA		-	_	2.4	V	
				V _{CE} = 2 V, I _{OUT} = 250 mA		-	_	2.7		
				V _{CE} = 2 V, I _{OUT} = 300 mA		_	_	3.0		
Input Voltage (Output On)	ULN2804AP / AFW			V _{CE} = 2 V, I _{OUT} = 125 mA		_	_	5.0		
(4)				V _{CE} = 2 V, I _{OUT} = 200 mA		_	_	6.0		
				V _{CE} = 2 V, I _{OUT} = 275 mA		_	_	7.0		
				V _{CE} = 2 V, I _{OUT} = 350 mA		_	_	8.0		
DC Current Tra	ansfer Ratio	h _{FE}	2	V _{CE} = 2 V, I _{OUT} = 350 mA		1000	_	_		
Clamp Diode Reverse Current		I _R	6	Ta = 25°C	(Note)	_	_	50	- μΑ	
				Ta = 85°C	(Note)	_	_	100		
Clamp Diode F	p Diode Forward Voltage V_F 7 I_F = 350 mA		_	_	2.0	V				
Input Capacitance		C _{IN}	_			_	15	_	pF	
Turn-On Delay		ton		R _L = 125 Ω, V _C	_{OUT} = 50 V	_	0.1	_	– µs	
Turn-Off Delay		t _{OFF}	t _{OFF} 8		_{OUT} = 50 V	_	0.2	_		

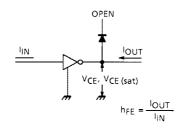
Note: $V_R = V_R MAX$.

TEST CIRCUIT

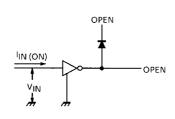
1. I_{CEX}



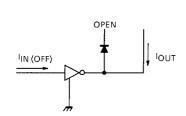
2. V_{CE (sat)}, h_{FE}



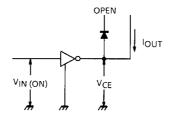
3. I_{IN (ON)}



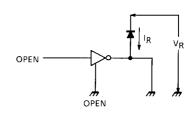
4. I_{IN} (OFF)



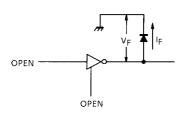
5. V_{IN} (ON)



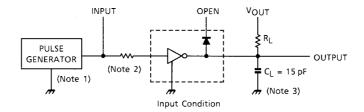
6. I_R

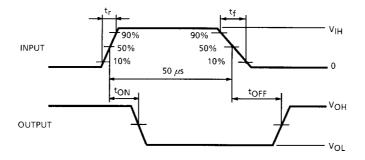


7. V_F



8. ton, toff





Note 1: Pulse Width 50 µs, Duty Cycle 10%

Output Impedance 50 Ω , $t_r \le 5$ ns, $t_f \le 10$ ns

Note 2: See below.

INPUT CONDITION

TYPE NUMBER	R1	V _{IH}
ULN2803AP / AFW	0Ω	3 V
ULN2804AP / AFW	0Ω	8 V

Note 3: C_L includes probe and jig capacitance

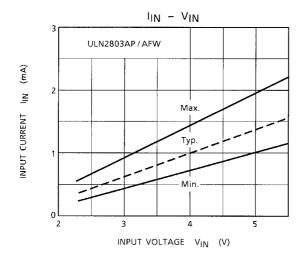
PRECAUTIONS for USING

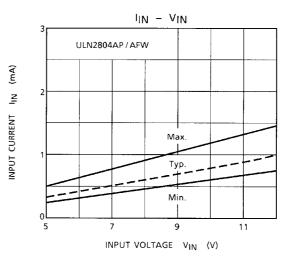
This IC does not integrate protection circuits such as overcurrent and overvoltage protectors.

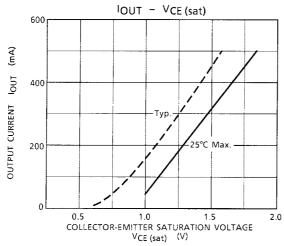
Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

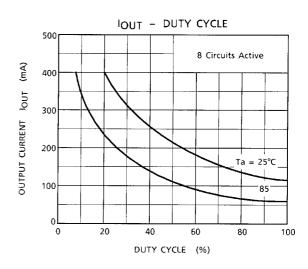
Utmost care is necessary in the design of the output line, COMMON and GND line since IC may be destroyed due to short–circuit between outputs, air contamination fault, or fault by improper grounding.

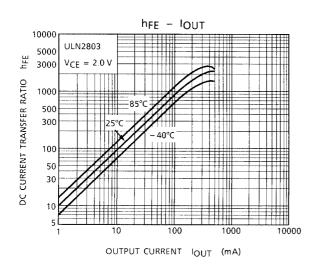
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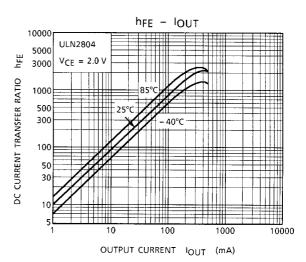




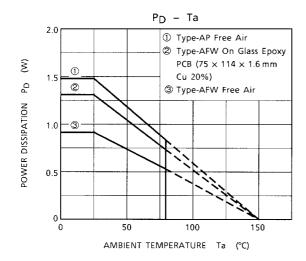








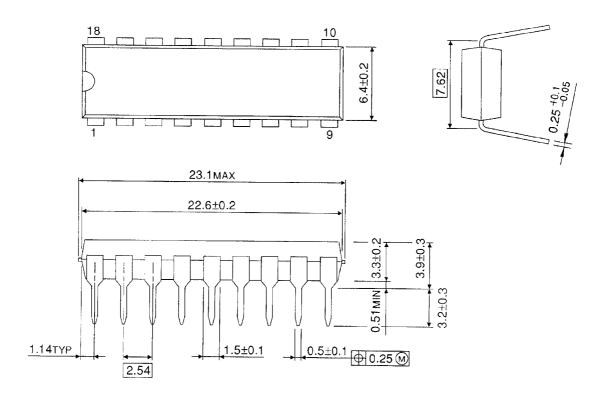
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PACKAGE DIMENSIONS

DIP18-P-300-2.54F Unit: mm

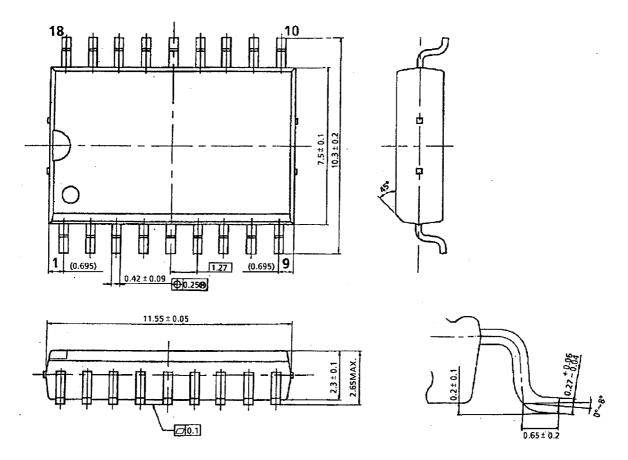


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Weight: 1.478 g (Typ.)

PACKAGE DIMENSIONS

SOL18-P-300-1.27 Unit: mm



Weight: 0.48 g (Typ.)

RESTRICTIONS ON PRODUCT USE

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